

Product Summary

BV_{DSS}	$R_{DS(ON)}$	I_D $T_C = +25^\circ C$
60V	16m Ω @ $V_{GS} = 10V$	68A
	24m Ω @ $V_{GS} = 4.5V$	55A

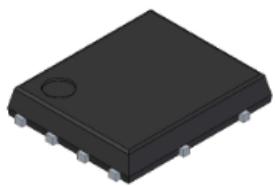
Description and Applications

This MOSFET has been designed to meet the stringent requirements of automotive applications. It is qualified to AEC-Q101, supported by a PPAP and is ideal for use in:

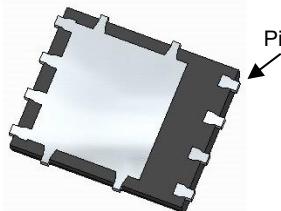
- Power management
- DC-DC converters
- Motor control

Site 1:

PowerDI5060-8



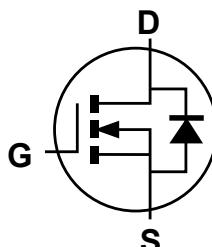
Top View



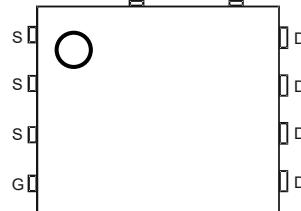
Bottom View

Mechanical Data

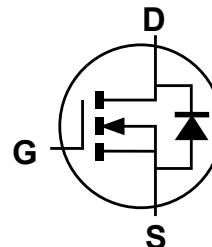
- Package: PowerDI®5060-8
- Package Material: Molded Plastic, "Green" Molding Compound. UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminal Finish - Matte Tin Annealed over Copper Leadframe. Solderable per MIL-STD-202, Method 208 ⑧③
- Weight: 0.097 grams (Approximate)



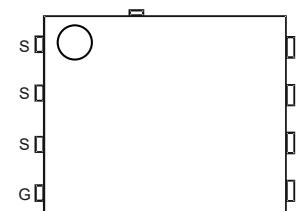
Internal Schematic



Top View
Pin Configuration



Internal Schematic



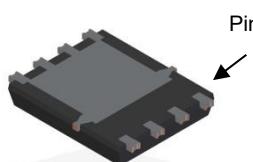
Top View
Pin Configuration

Site 2:

PowerDI5060-8/SWP (Type UX)



Top View



Bottom View

Ordering Information (Note 4)

Orderable Part Number	Package	Packing	
		Qty.	Carrier
DMTH6016LPSQ-13	PowerDI5060-8	2,500	Tape & Reel
DMTH6016LPSQ-13	PowerDI5060-8/SWP (Type UX)	2,500	Tape & Reel

Notes:

1. EU Directive 2002/95/EC (RoHS), 2011/65/EU (RoHS 2) & 2015/863/EU (RoHS 3) compliant. All applicable RoHS exemptions applied.
2. See <https://www.diodes.com/quality/lead-free/> for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.
3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.
4. For packaging details, go to our website at <https://www.diodes.com/design/support/packaging/diodes-packaging/>.

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DMTH6016LPSQ

Document number: DS38518 Rev. 6 - 2

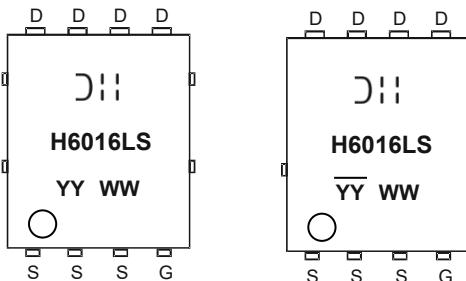
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www.diodes.com

October 2025

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Marking Information



DI = Manufacturer's Marking
 H6016LS = Product Type Marking Code
 YYWW = Date Code Marking
 YY or YY = Last Two Digits of Year (ex: 25 = 2025)
 WW = Week Code (01 to 53)

Maximum Ratings (@ $T_A = +25^\circ\text{C}$, unless otherwise specified.)

Characteristic			Symbol	Value	Unit
Drain-Source Voltage			V_{DSS}	60	V
Gate-Source Voltage			V_{GSS}	± 20	V
Continuous Drain Current (Note 6) $V_{GS} = 10\text{V}$	$T_C = +25^\circ\text{C}$ $T_C = +100^\circ\text{C}$		I_D	68 48	A
Continuous Drain Current (Note 5) $V_{GS} = 10\text{V}$	Steady State	$T_A = +25^\circ\text{C}$ $T_A = +100^\circ\text{C}$	I_D	12.3 8.7	A
Pulsed Drain Current (10 μs Pulse, Duty Cycle = 1%)			I_{DM}	271	A
Maximum Continuous Body Diode Forward Current (Note 6)			I_S	68	A
Avalanche Current, $L = 0.1\text{mH}$			I_{AS}	15.3	A
Avalanche Energy, $L = 0.1\text{mH}$			E_{AS}	11.7	mJ

Thermal Characteristics

Characteristic		Symbol	Value	Unit
Total Power Dissipation (Note 5)	$T_A = +25^\circ\text{C}$	P_D	3.64	W
Thermal Resistance, Junction to Ambient (Note 5)	Steady State	$R_{\theta JA}$	41.2	$^\circ\text{C}/\text{W}$
Total Power Dissipation (Note 6)	$T_C = +25^\circ\text{C}$	P_D	110	W
Thermal Resistance, Junction to Case (Note 6)		$R_{\theta JC}$	1.36	$^\circ\text{C}/\text{W}$
Operating and Storage Temperature Range		T_J, T_{STG}	-55 to +175	$^\circ\text{C}$

Notes: 5. Device mounted on FR-4 substrate PC board, 2oz copper, with thermal bias to bottom layer 1 inch square copper plate.
 6. Thermal resistance from junction to soldering point (on the exposed drain pad).

Electrical Characteristics (@ $T_A = +25^\circ\text{C}$, unless otherwise specified.)

Characteristic	Symbol	Min	Typ	Max	Unit	Test Condition
OFF CHARACTERISTICS (Note 7)						
Drain-Source Breakdown Voltage	BV_{DSS}	60	—	—	V	$\text{V}_{\text{GS}} = 0, \text{I}_D = 250\mu\text{A}$
Zero Gate Voltage Drain Current	I_{DSS}	—	—	1	μA	$\text{V}_{\text{DS}} = 48\text{V}, \text{V}_{\text{GS}} = 0$
Gate-Source Leakage	I_{GSS}	—	—	± 100	nA	$\text{V}_{\text{GS}} = \pm 20\text{V}, \text{V}_{\text{DS}} = 0$
ON CHARACTERISTICS (Note 7)						
Gate Threshold Voltage	$\text{V}_{\text{GS(TH)}}$	1	—	2.5	V	$\text{V}_{\text{DS}} = \text{V}_{\text{GS}}, \text{I}_D = 250\mu\text{A}$
Static Drain-Source On-Resistance	$\text{R}_{\text{DS(ON)}}$	—	12.4	16	$\text{m}\Omega$	$\text{V}_{\text{GS}} = 10\text{V}, \text{I}_D = 20\text{A}$
		—	18.2	24		$\text{V}_{\text{GS}} = 4.5\text{V}, \text{I}_D = 18\text{A}$
Diode Forward Voltage	V_{SD}	—	0.7	1.2	V	$\text{V}_{\text{GS}} = 0, \text{I}_S = 1\text{A}$
DYNAMIC CHARACTERISTICS (Note 8)						
Input Capacitance	C_{iss}	—	864	—	pF	$\text{V}_{\text{DS}} = 30\text{V}, \text{V}_{\text{GS}} = 0, \text{f} = 1\text{MHz}$
Output Capacitance	C_{oss}	—	282	—		
Reverse Transfer Capacitance	C_{rss}	—	27	—	Ω	$\text{V}_{\text{DS}} = 0, \text{V}_{\text{GS}} = 0, \text{f} = 1\text{MHz}$
Gate Resistance	R_G	—	1.3	—		
Total Gate Charge ($\text{V}_{\text{GS}} = 4.5\text{V}$)	Q_g	—	8.4	—	nC	$\text{V}_{\text{DS}} = 30\text{V}, \text{I}_D = 10\text{A}$
Total Gate Charge ($\text{V}_{\text{GS}} = 10\text{V}$)	Q_g	—	17	—		
Gate-Source Charge	Q_{gs}	—	3.1	—	ns	$\text{V}_{\text{GS}} = 10\text{V}, \text{V}_{\text{DS}} = 30\text{V}, \text{R}_G = 6\Omega, \text{I}_D = 10\text{A}$
Gate-Drain Charge	Q_{gd}	—	4.3	—		
Turn-On Delay Time	$\text{t}_{\text{D(ON)}}$	—	3.4	—	ns	$\text{V}_{\text{GS}} = 10\text{V}, \text{V}_{\text{DS}} = 30\text{V}, \text{R}_G = 6\Omega, \text{I}_D = 10\text{A}$
Turn-On Rise Time	t_R	—	5.2	—		
Turn-Off Delay Time	$\text{t}_{\text{D(OFF)}}$	—	13	—	ns	$\text{I}_F = 10\text{A}, \text{di/dt} = 100\text{A}/\mu\text{s}$
Turn-Off Fall Time	t_F	—	7	—		
Reverse-Recovery Time	t_{RR}	—	22	—	nC	$\text{I}_F = 10\text{A}, \text{di/dt} = 100\text{A}/\mu\text{s}$
Reverse-Recovery Charge	Q_{RR}	—	11	—		

Notes: 7. Short duration pulse test used to minimize self-heating effect.

8. Guaranteed by design. Not subject to product testing.

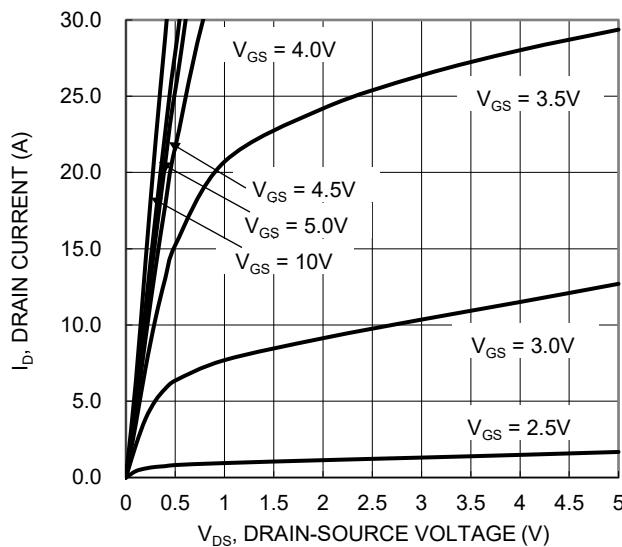


Figure 1. Typical Output Characteristic

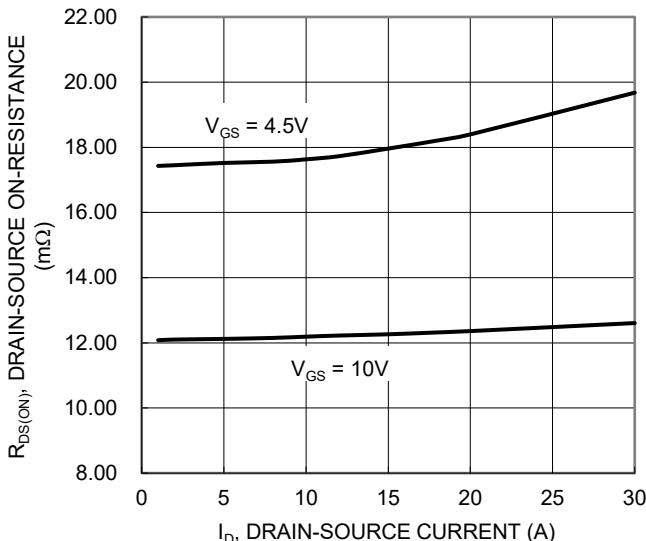


Figure 3. Typical On-Resistance vs Drain Current and Gate Voltage

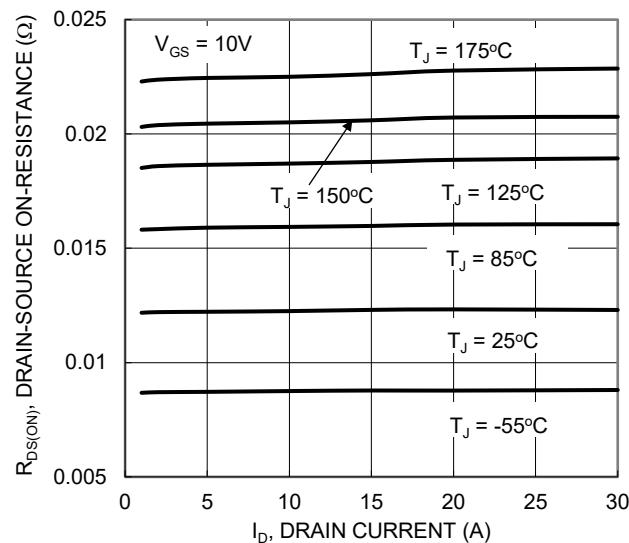


Figure 5. Typical On-Resistance vs Drain Current and Temperature

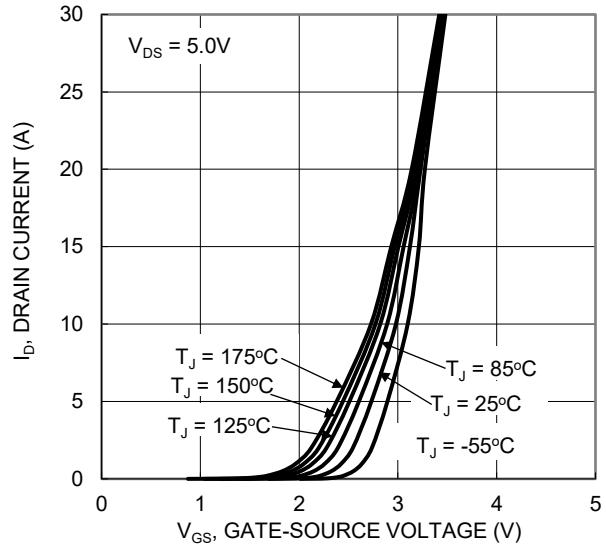


Figure 2. Typical Transfer Characteristic

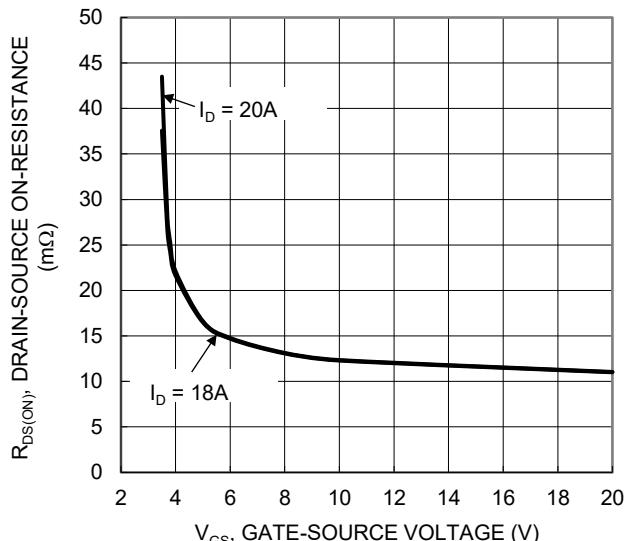


Figure 4. Typical Transfer Characteristic

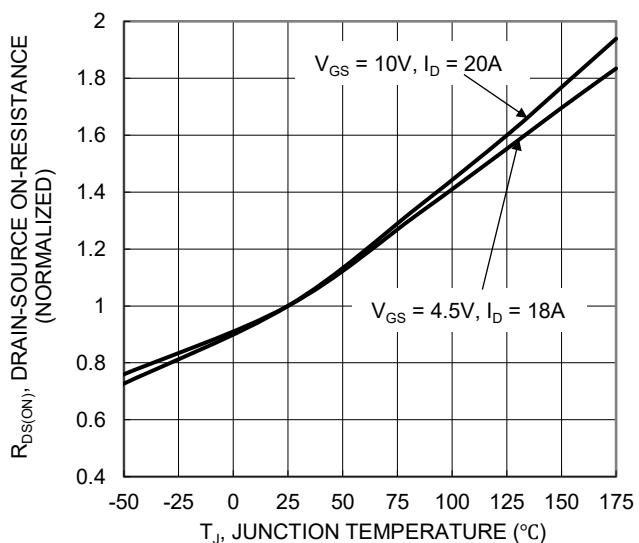


Figure 6. On-Resistance Variation with Temperature

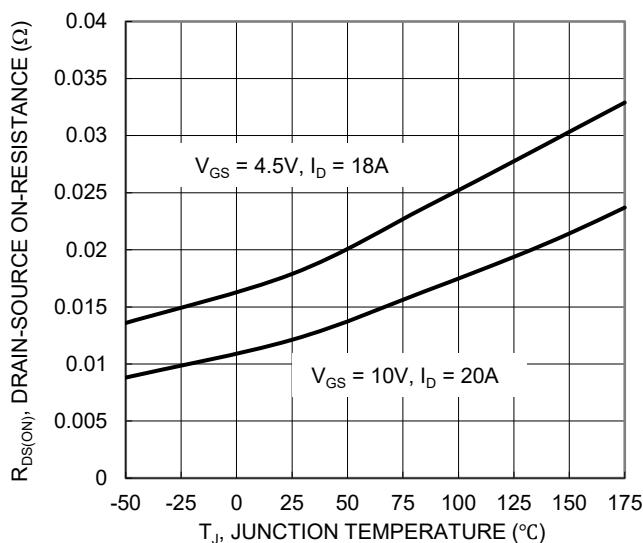


Figure 7. On-Resistance Variation with Temperature

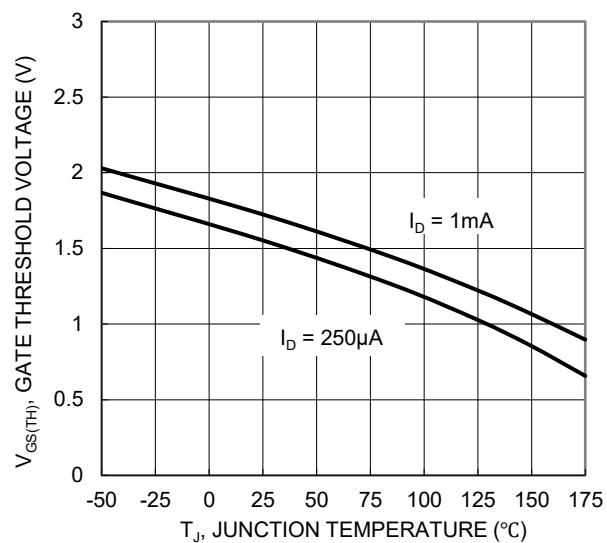


Figure 8. Gate Threshold Variation vs Junction Temperature

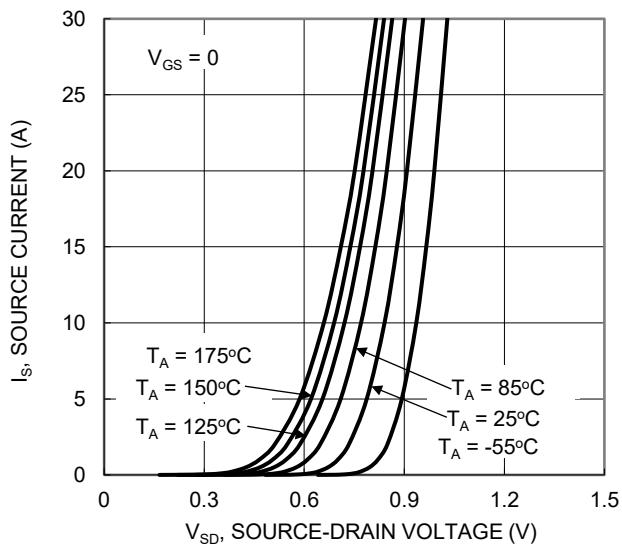


Figure 9. Diode Forward Voltage vs. Current

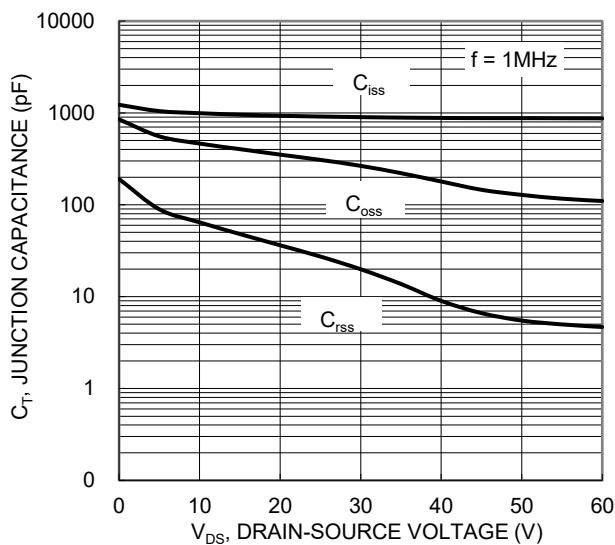


Figure 10 Typical Junction Capacitance

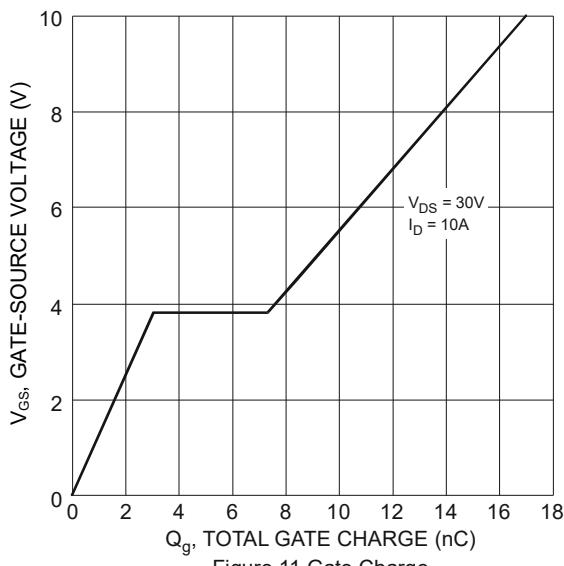


Figure 11 Gate Charge

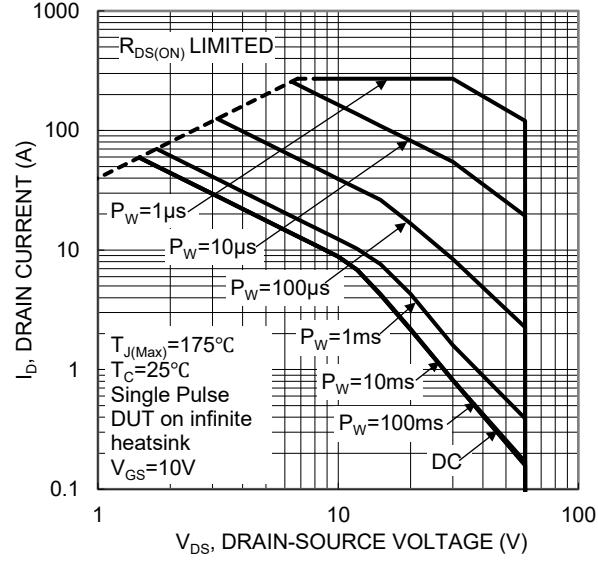


Figure 12. SOA, Safe Operation Area

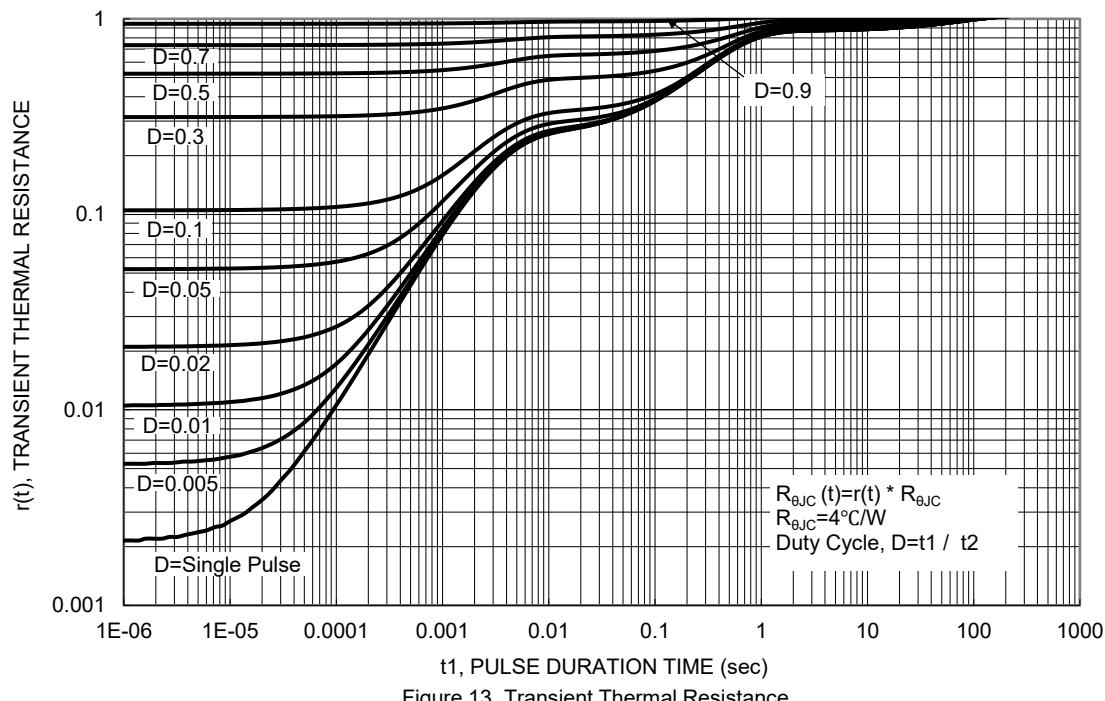


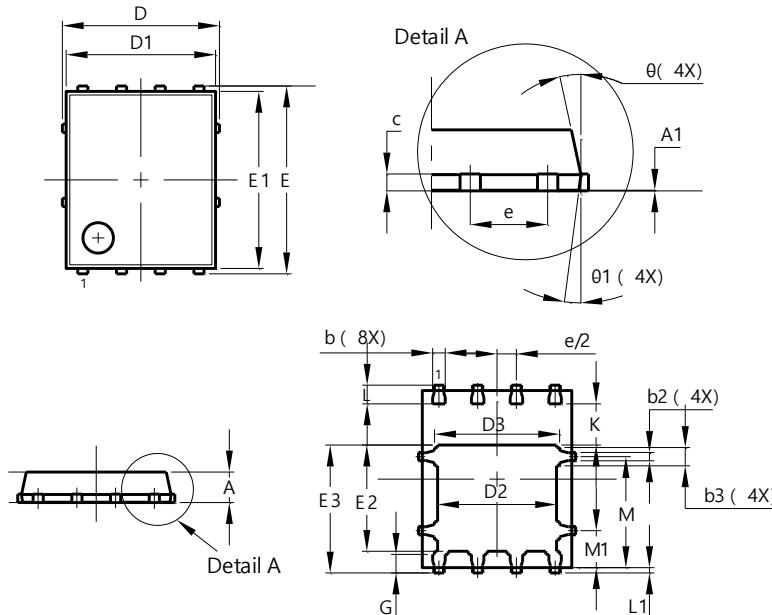
Figure 13. Transient Thermal Resistance

Package Outline Dimensions

Please see <http://www.diodes.com/package-outlines.html> for the latest version.

Site 1:

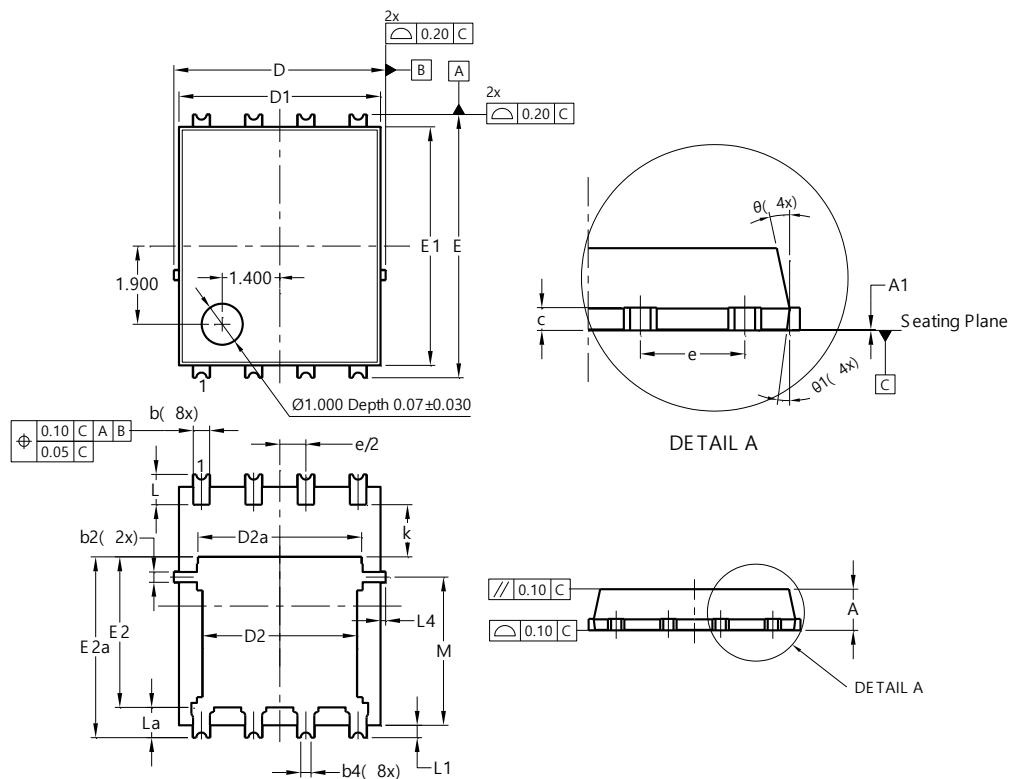
PowerDI5060-8



PowerDI5060-8			
Dim	Min	Max	Typ
A	0.90	1.10	1.00
A1	0.00	0.05	—
b	0.33	0.51	0.41
b2	0.200	0.350	0.273
b3	0.40	0.80	0.60
c	0.230	0.330	0.277
D	5.15 BSC		
D1	4.70	5.10	4.90
D2	3.70	4.10	3.90
D3	3.90	4.30	4.10
E	6.15 BSC		
E1	5.60	6.00	5.80
E2	3.28	3.68	3.48
E3	3.99	4.39	4.19
e	1.27 BSC		
G	0.51	0.71	0.61
K	0.51	—	—
L	0.51	0.71	0.61
L1	0.100	0.200	0.175
M	3.235	4.035	3.635
M1	1.00	1.40	1.21
Θ	10°	12°	11°
Θ1	6°	8°	7°

Site 2:

PowerDI5060-8/SWP (Type UX)



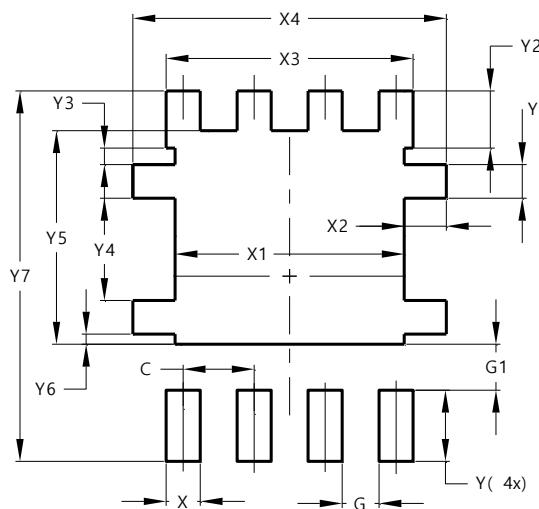
PowerDI5060-8/SWP (Type UX)			
Dim	Min	Max	Typ
A	0.90	1.10	1.00
A1	0	0.05	--
b	0.30	0.50	0.41
b2	0.20	0.35	0.25
b4	0.25REF		
c	0.230	0.330	0.277
D	5.15 BSC		
D1	4.70	5.10	4.90
D2	3.56	3.96	3.76
D2a	3.78	4.18	3.98
E	6.40 BSC		
E1	5.60	6.00	5.80
E2	3.46	3.86	3.66
E2a	4.195	4.595	4.395
e	1.27BSC		
k	1.05	--	--
L	0.635	0.835	0.735
La	0.635	0.835	0.735
L1	0.200	0.400	0.300
L4	0.025	0.225	0.125
M	3.205	4.005	3.605
θ	10°	12°	11°
θ1	6°	8°	7°

Suggested Pad Layout

Please see <http://www.diodes.com/package-outlines.html> for the latest version.

Site 1:

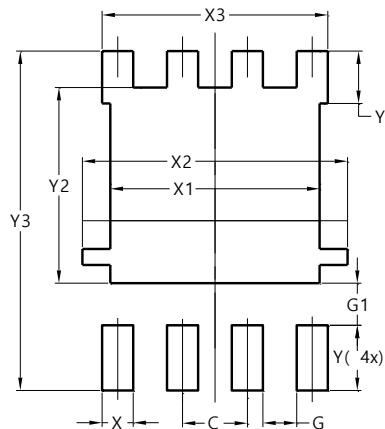
PowerDI5060-8



Dimensions	Value (in mm)
C	1.270
G	0.660
G1	0.820
X	0.610
X1	4.100
X2	0.755
X3	4.420
X4	5.610
Y	1.270
Y1	0.600
Y2	1.020
Y3	0.295
Y4	1.825
Y5	3.810
Y6	0.180
Y7	6.610

Site 2:

PowerDI5060-8/SWP (Type UX)



Dimensions	Value (in mm)
C	1.270
G	0.660
G1	0.820
X	0.610
X1	4.100
X2	5.190
X3	4.420
Y	1.270
Y1	1.020
Y2	3.810
Y3	6.610

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